



* Starting from 2007, MQA's accreditation is perpetual unless stated otherwise. All accredited qualifications are subject to periodic maintenance audit to ensure continuous improvement. If the accreditation of a qualification is revoked, the cessation date will be displayed in the Malaysian Qualifications Register. Qualifications previously accredited under National Accreditation Board of (Lembaga Akreditasi Negara, LAN) have a validity period of 5 years and this information is stated in the MQR for reference purposes.

* The verification of accreditation status of a programme will not be performed by MQA. This printed statement is sufficient for any related business.

Diploma in Technology (Materials and Manufacturing Engineering)


Reference Number : AA0046
Certificate Number : 08164
Name of Qualification : Diploma in Technology (Materials and Manufacturing Engineering)
Date of Accreditation* : 18/12/2008 to 21/08/2019
(dd/mm/yyyy)
Compliance Audit : MJA Meeting on 30/6/2020 decided to maintain Full Accreditation.
Name of Institution : Tunku Abdul Rahman University of Management and Technology (TAR UMT)
Address : Jalan Genting Klang
 Setapak
 53300
 Wilayah Persekutuan Kuala Lumpur
Telephone Number : 03-4145 0123
Fax Number : -
E-mail : info@tarc.edu.my
Website : www.tarc.edu.my
Type : Diploma
MQF Level : 4
NEC Field (National Education Code) : 0714 (Mechanics and metal trades)
Number of Credits : 98
Mode of Study : Full Time

Duration of Study (years)	Full Time	Weeks/Semester	Semesters	Duration
	Long	17	4	2 year/s
	Short	9	2	

Starting	Weeks/Semester	Semesters	Industrial Training	Years	Credits
18/12/2008	14 + 7	5 + 2	-	2 tahun/years 4 bulan/months	103
24/5/2018	17 + 9	4 + 2	-	2	98

Mode of Delivery : Conventional

Remark(s) : Previous HEP Name:Tunku Abdul Rahman University College, Kuala Lumpur (Main Campus). Latest HEP Name effective 7/11/2022. Program Cessation Date: 22/08/2019

*NA : Not Available

DISCLAIMER: The Malaysian Government and the Malaysian Qualifications Agency shall not be liable for any loss or damage howsoever arising from the use of any information contained herein.